RZ/A2M Group

JPEG Codec Unit "JCU" Sample Application

Introduction

This application note describes the sample application that decodes JPEG compressed image and encodes to JPEG compressed image using JPEG codec unit (JCU).

Target Device

RZ/A2M

Contents

1. Specifications

Table 1.1 lists the Peripheral Functions and Their Applications, and Figure 1.1 shows the Operation Overview.

Table 1.1 Peripheral device used

Peripheral device	Usage
JPEG Codec Unit(JCU)	Converts image data.
Interrupt controller(INTC)	The processor will receive interrupts when decoding or encoding is completed, failed, or paused.
Serial Communication Interface with FIFO(SCIF) Ch2	Output sample code message.

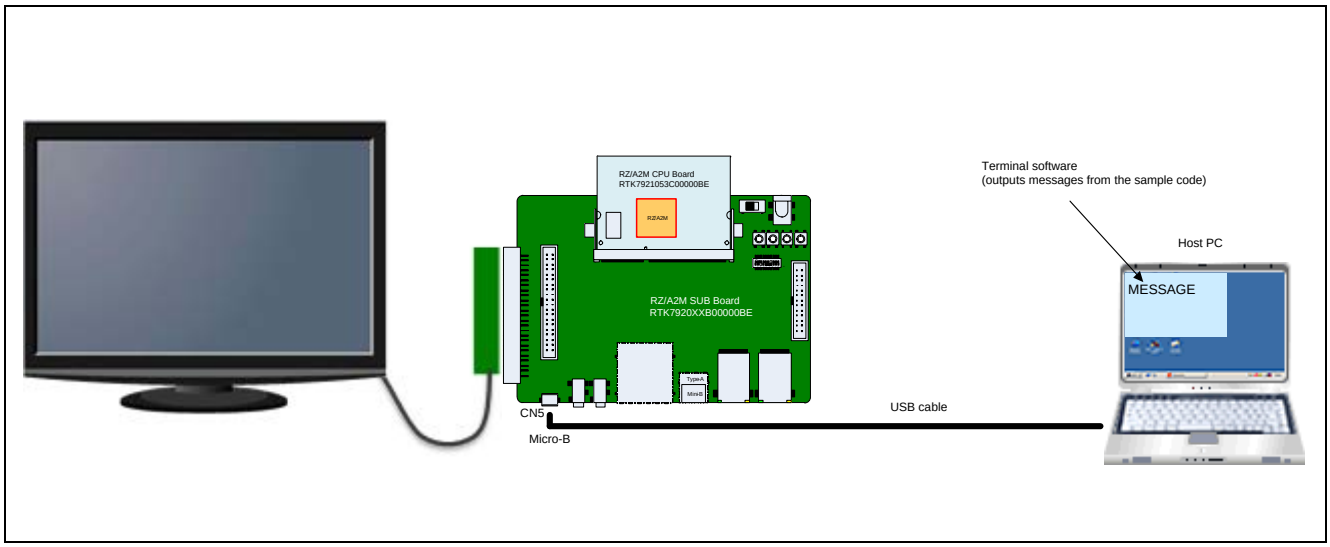

Figure 1.1 Operation check conditions

2. Operation Confirmation Conditions

Table 2.1. Operation Confirmation Conditions (1/2)

item	Contents
MCU used	RZ/A2M
Operating frequency (Note)	CPU Clock (Iϕ) : 528MHz Image processing clock (Gϕ) : 264MHz Internal Bus Clock (Bϕ) : 132MHz Peripheral Clock 1 (P1ϕ) : 66MHz Peripheral Clock 0 (P0ϕ) : 33MHz QSPI0_SPCLK : 66MHz CKIO : 132MHz
Operating voltage	Power supply voltage (I/O): 3.3 V Power supply voltage (either 1.8V or 3.3V I/O (PVcc SPI)) : 3.3V Power supply voltage (internal): 1.2 V
Integrated development environment	e2 studio V7.4.0
C compiler	"GNU Arm Embedded Tool chain 6-2017-q2-update" compiler options(except directory path) Release: -mcpu=cortex-a9 -march=armv7-a -marm -mlittle-endian -mfloat-abi=hard -mfpu=neon -mno-unaligned-access -Os -ffunction-sections -fdata-sections -Wunused -Wuninitialized -Wall -Wextra -Wmissing-declarations -Wconversion -Wpointer-arith -Wpadded -Wshadow -Wlogical-op -Waggregate-return -Wfloat-equal -Wnull-dereference -Wmaybe-uninitialized -Wstack-usage=100 -fabi-version=0 Hardware Debug: -mcpu=cortex-a9 -march=armv7-a -marm -mlittle-endian -mfloat-abi=hard -mfpu=neon -mno-unaligned-access -Og -ffunction-sections -fdata-sections -Wunused -Wuninitialized -Wall -Wextra -Wmissing-declarations -Wconversion -Wpointer-arith -Wpadded -Wshadow -Wlogical-op -Waggregate-return -Wfloat-equal -Wnull-dereference -Wmaybe-uninitialized -g3 -Wstack-usage=100 -fabi-version=0

Note: The operating frequency used in clock mode 1 (Clock input of 24MHz from EXTAL pin)

Table 2.2. Operation Confirmation Conditions (2/2)

Operation mode	Boot mode 3 (Serial Flash boot 3.3V)
Terminal software communication settings	• Communication speed: 115200bps • Data length: 8 bits • Parity: None • Stop bits: 1 bit • Flow control: None
Board to be used	RZ/A2M CPU board RTK7921053C00000BE RZ/A2M SUB board RTK79210XXB00000BE
Device (functionality to be used on the board)	• Serial flash memory allocated to SPI multi-I/O bus space (channel 0) Manufacturer : Macronix Inc. Model Name : MX25L51245GXD • RL78/G1C (Convert between USB communication and serial communication to communicate with the host PC.) • LED1

3. Sample of JPEG Decoding and Showing

There is the main of application in "R_JCU_SampleDecode" function in "decode_sample.c" file.

The above image is a JPEG image in the sample.

3.1 Operation Outline

Figure 3-1 shows the sequence of JPEG decoding and showing sample.

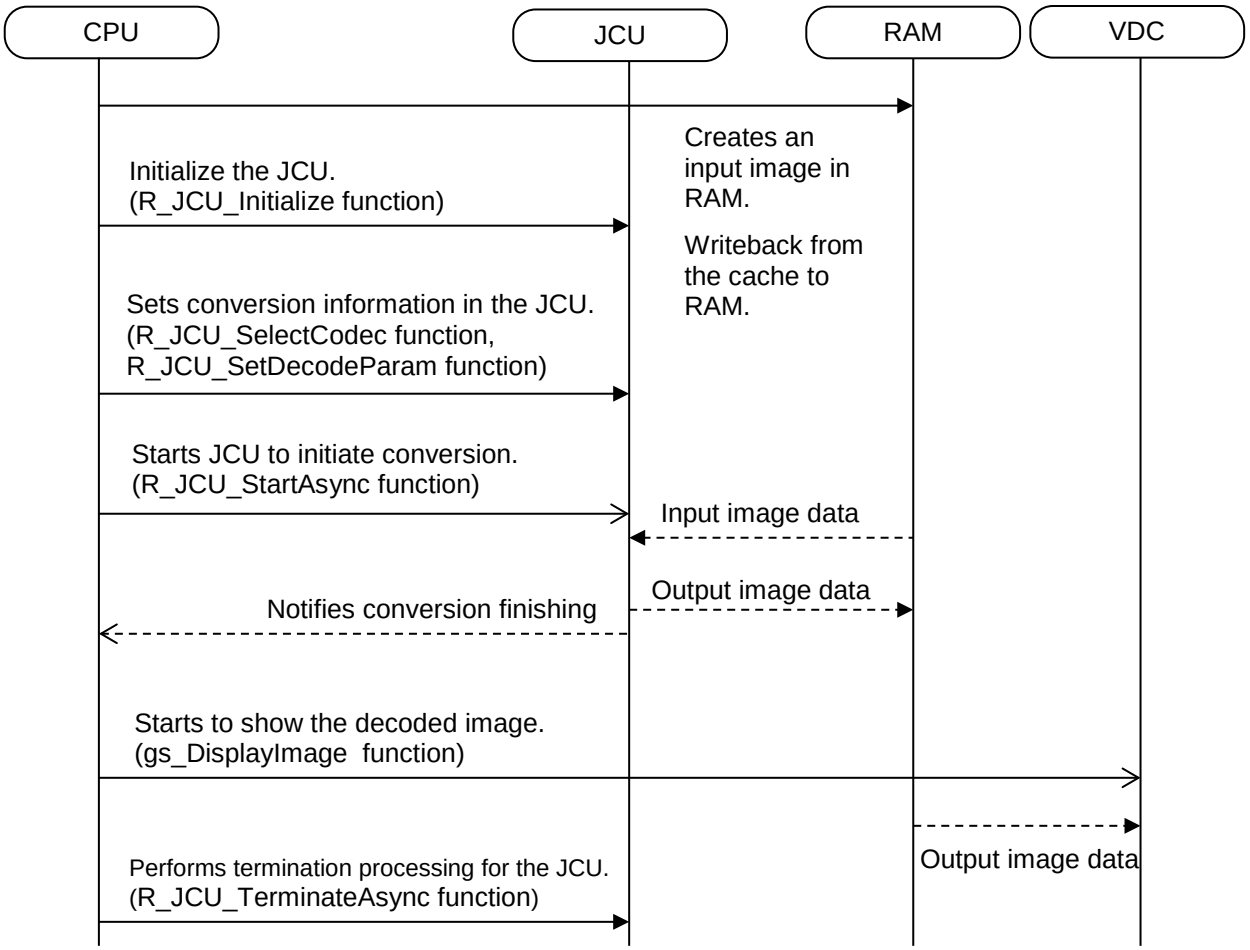

Figure 3-1 Sequence of JPEG decoding and showing sample

4. Sample of JPEG Encoding

There is the main of application in "R_JCU_SampleDecodeEncode" function in "decode_encode_sample.c" file.

4.1 Operation Outline

Figure 3-1 shows the sequence of JPEG encoding sample. Decoding is done before encoding to prepare the data to be encoded.

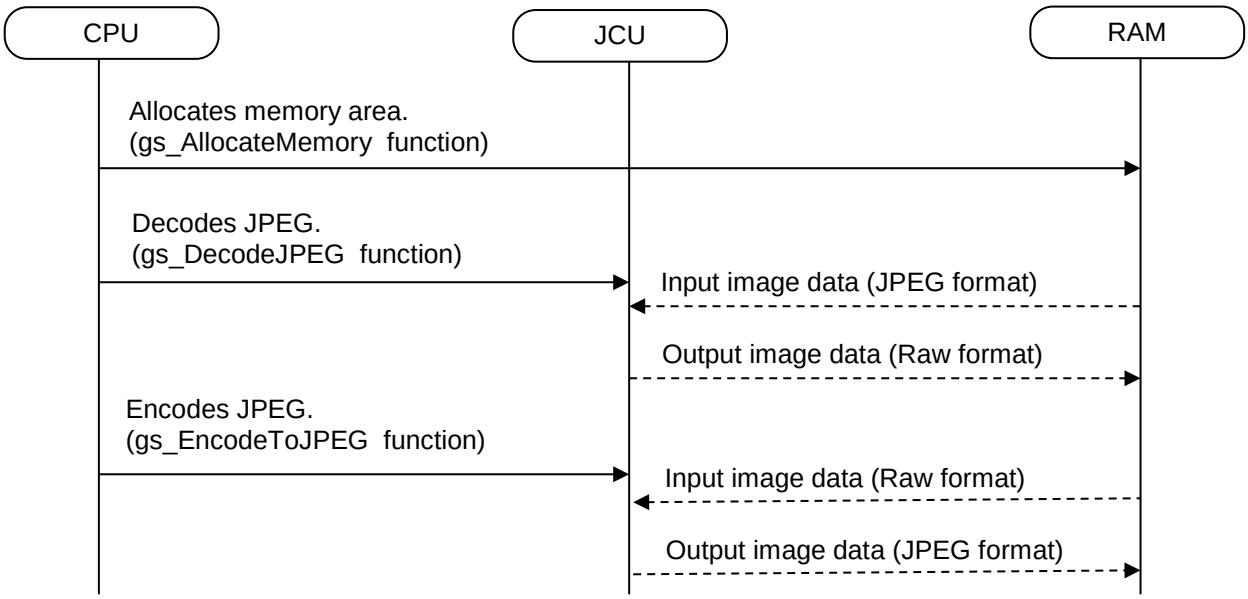

Figure 4-1 Sequence of JPEG encoding sample

5. Reference Documents

R01AN4456EJ : JPEG Codec Unit "JCU" Driver Example Application Note

The latest version can be downloaded from the Renesas Electronics website.

6. Used open source software and licenses

Open source software used in this package and license of them are shown as following:

- newlib is used under the license described in following site:
  https://www.sourceware.org/newlib/COPYING.NEWLIB
- FreeRTOS is used under MIT license described in following site:
  https://www.freertos.org/a00114.html

7. Reference Documents

User's Manual: Hardware

RZ/A2M Group User's Manual: Hardware
The latest version can be downloaded from the Renesas Electronics website.

RTK7921053C00000BE (RZ/A2M CPU board) User's Manual
The latest version can be downloaded from the Renesas Electronics website.

RTK79210XXB00000BE (RZ/A2M SUB board) User's Manual
The latest version can be downloaded from the Renesas Electronics website.

ARM Architecture Reference Manual ARMv7-A and ARMv7-R edition Issue C
The latest version can be downloaded from the ARM website.

ARM CortexTM-A9 Technical Reference Manual Revision: r4p1
The latest version can be downloaded from the ARM website.

ARM Generic Interrupt Controller Architecture Specification - Architecture version 2.0
The latest version can be downloaded from the ARM website.

ARM CoreLinkTM Level 2 Cache Controller L2C-310 Technical Reference Manual Revision: r3p3
The latest version can be downloaded from the ARM website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

User's Manual: Development Tools

Integrated development environment e2studio User’s Manual can be downloaded from the Renesas Electronics website.
The latest version can be downloaded from the Renesas Electronics website.

Revision History

Rev.	Date	Description	
		Page	Summary
1.10	May. 17, 2019	P3	Table 2.1. Operation Confirmation Conditions (1/2) Remove compiler option “-mthumb-interwork”
1.03	Apr. 15, 2019	p3	Updated the confirmed version of integrated development environment
		p7	Added section 6
1.02	Dec. 28, 2018	-	The project base is updated.
1.00	Sep.14, 2018	-	First edition issued

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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